



Product / Process Change Notice

No.: Z200-PCN-DM201505-01-A

Date: 05/04/2015

Change Title : W25Q40EW "E-Series" (90nm) to replace W25Q40BW "B-Series" (90nm) 4Mb 1.8V SpiFlash® Memories

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Package Assembly Testing Others

Affected Product(s) :

W25Q40BWSNIG ,W25Q40BWSVIG ,W25Q40BWUXIE ,W25Q40BWUXIG

Description of Change(s)

The W25Q40EW 4Mb 1.8V SpiFlash® Memories use Winbond's 90nm Flash technology. It is function-compatible W25Q40BW 90nm devices offering improved performance, features and availability.

Reason for Change(s) :

Improve features which as below,

- a) Command backward compatible with W25Q40BW (same Superset Instruction Set)
- b) Clock operation up to 104MHz
- c) Lower power consumption
- d) SPI with Single / Dual / Quad / QPI mode
- e) Flexible architecture with 4KB sectors

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change

Function : No Change

Reliability : No Concern (Please refer to the attachment I)

Hazardous Substances: No Concern (Please refer to the attachment II)

Qualification Plan/ Results :

Based on Winbond W25Q40EW Serial Flash Reliability report, the new product meets our criteria and no quality concern (refer to Attachment I in details)

Implementation Plan :

Please refer to attachment III in details.

Date Code: _____ onward Lot No: _____ onward Proposed first ship date: 08/04/2015



Originator: (QA Sec. Manager)	<i>YH Cheng</i>	Approval: (QA Dept. Manager)	<i>YH Cheng</i>	Approval: (QRA Director)	<i>Genon Chen</i>
Contact for Questions & Concerns	Name: <u>Betty Huang</u> TEL: <u>886-3-5678168</u> (ext.86549) FAX: <u>886-3-5796124</u> Address : <u># 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan</u> E-mail: <u>Hyhuang8@winbond.com</u>				

Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

<input type="checkbox"/> Approval	<input type="checkbox"/> Disapproval	<input type="checkbox"/> Conditional Approval : _____.
Comment:		
Date: _____		
Dept. name: _____		
Person in charge: _____		





Winbond Electronics Corporation

No.539, Sec.2 Wenxing Rd.
Jhubei City, Hsinchu,
Taiwan, R.O.C.

Product Obsolescence Notice

W25Q40EW SpiFlash Memories

Notification Date: May 04, 2015

Dear Valued Customer,

This letter is to notify you of Winbond’s intention to terminate production of the W25Q40BW SpiFlash memory. And replace it with the W25Q40EW. Replacement part numbers are listed below:

Winbond Current PN (90nm B-Series)	Winbond Primary Replacement PN (90nm E-Series)
W25Q40BWSNIG	W25Q40EWSNIG
W25Q40BWSVIG	W25Q40EWSVIG
W25Q40BWUXIE	W25Q40EWUXIE
W25Q40BWUXIG	W25Q40EWUXIE

The W25Q40EW device features:

Features

- a) Command backward compatible with W25Q40BW (same Superset Instruction Set)
- b) Clock operation up to 104MHz
- c) Lower power consumption
- d) SPI with Single / Dual / Quad / QPI mode
- e) Flexible architecture with 4KB sectors

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25Q40BW	May./04/2015	Nov./04/2015	May./04/2016	W25Q40EW	Mar./16/2015	Apr./30/2015

Eddy Hung
Assistant Vice President of Flash Marketing